

EK79631 EPD Driver

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## S1280\*G840 EPD Driver

### 1. GENERAL DESCRIPTION

The EK79631 is an EPD IC max for 1280\*840 active matrix display, include Source driver and Gate driver. It also provides cascade function for dot expansion.

The Source driver is a selectable 1280, 1200, 1024, 960 or 800 bit long 2-bit wide serial-input parallel-output driver with level conversion on each parallel output which converts the 2 digital bits into positive, GND, or negative analog output voltages. An 16-bit input bus simultaneously inputs 8 groups of 2 bits each. It consists of a Bi-Directional Shift Data Inputs, Transfer Latch, and 1280 bit Level Shifter/Output Driver. Each "S[1] .. S[1280]" pin is switched to one of [VPOS, GND, VNEG], according to the D15...D0 logic levels clocked into the Source driver, modified by the OE pin.

After a start pulse of Gate driver is triggered, output pins will output high-driving voltage pulses sequentially for the gate signals of the display. It supports 840/825/768/758/720/704/640/600/480 channels, shift up/down selection.

### 2. FEATURES

#### Source

- CMOS Technology
- 1280/1200/1024/960/800 Output Channels Selectable
- Drives Segment or Active Matrix Displays
- +/-15 Volt Source Output Driver Supply Voltage
- Logical Interface: 1.7V ~ 3.6V
- Maximum Operating Frequency: 60MHz / 48MHz (VCC = 2.5V ~ 3.6V / 1.7V ~ 2.5V)
- Bi-Directional Shift 16-bit Data Inputs

### Gate

- 840/825/768/758/720/704/640/600/480 Output Channels Selectable
- Built-in Bi-direction Shift Register
- Logical Interface: 1.7V ~ 3.6V
- Output Supply Voltage: VGL + 49V
- Maximum Operation Frequency: 200KHZ
- CMOS Silicon Gate

### Package

COG type

## 3. BLOCK DIAGRAM

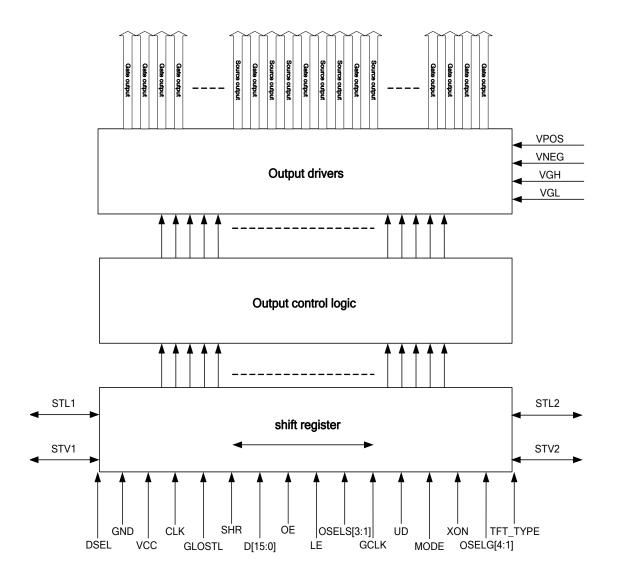


Figure 1. Block Diagram

## 4. PIN DESCRIPTION

Table 1. Pin Description

Pin Name	Pin Type			D	escrip	tion				
Source Driver										
CLK	Input		ver clock inpu							
	mpat		s are capture		1			ınal.		
STL1		SHR	Start Pulse		Start	Pulse Οι	ıtput			
OTLO	Bi-direction	Н	STL2			STL1				
STL2		L	STL1			STL2				
			rt pulse input.			1				
		SHR	GLOSTL s	-						
OL OCTI	Input with	Н		C' STL2						
GLOSTL	Pull High	L		C' STL1						
			me and synch							
		cascade u	me and synch	ironous	with the	e ilist ic	s start p	ouise ii	ipu	t in
			oe. Data inputs re	ad segu	entially	from SI1	2801 to	S[1]		
SHR	Input		ata inputs rea							
			nronous to clo				,			
		Source driver data input pins. They are latched on the rising edge of						edge of		
		CLK.								
D[15:0]	Input		Input port	DSE	L	N	ote			
D[13.0]	Input	8-bit	D00~D07	Н		D08~D15	should	be		
					tied t	o GND				
		16-bit	D00~015	L						
DOEL	lant	Data input		D00 I	D07					
DSEL	Input	DSEL=H: 8-bit, input port D00~D07 DSEL=L: 16-bit, input port D00~D15								
			ver outputs ei			F is logic	"Н"			
OE	Input with		rced to GND				, , ,			
	Pull Low		nronous to clo							
LE	Input		ver parallel la			nsparent	when hi	igh.		
	трис		nronous to clo							
S[1] ~ S[1280]	Output	Source dri	ver parallel o	outputs.	Range	is from	VNEG	to VP	os	. Always
-(1 -(1		Course to Gi	ND by setting tput channel s	OE to IC	ogic "L"	prior to p	ower s	witchir	ng o	n or off.
		OSELS				ELS3	chai	nnels		
OSELS1		X	X			H		280		
OSELS2	Input with	H	H	-		L		200		
OSELS3	Pull High	L	Н			L		024		
		Н	L			L	9	60		
		L	L			L	8	00		
Gate Driver										
GCLK	Input		r shift clock p		shift reg	gister data	a is shif	ted sy	nch	ronously
	, , ,	1	rising edge of		1 _					
STV1	D: " '	UD	Start Pulse		Start	Pulse Ou	ıtput			
STV2	Bi-direction	H	STV1			STV2				
3172		L	STV2		l "	STV1		.1		
			ate driver up/	down pu	iise dire	ection cor	ntrol and	a settii	ng c	ascade
UD	Input	sequence Display dri	input pin. ve outputs sh	ift from	G[1] to	G[840] w	hen set	t to "H	,,	
			ve outputs sh							

Pin Name	Pin Type	Description				
		TFT type select pin				
TFT_TYPE	Input with	TFT_TYPE TFT Note				
''''_''''	Pull Low	H PMOS Gate Output L pulse scan				
		L NMOS Gate Output H pulse scan				
MODE	Input with	Used as gate driver output mode selection pins.				
MODE	Pull Low	MODE = H: Normal single pulse.  MODE = L: Always keep VGL. (Always keep VGH when TFT_TYPE=H).				
		When XON input pin is 'L', all the output pins are forced to VGH level				
VON	Input with	(Forced to VGL when TFT_TYPE=H ). Also it has an internal pull high				
XON	Pull High	resistor, keep it to VCC is preferred when unused. The chip internal shift				
		register is not cleared when XON input is active.				
		Gate output channel select inputs.				
		OSELG1 OSELG2 OSELG3 OSELG4 channels				
		X				
OSELG1		H         H         L         825           L         H         H         L         768				
OSELG2	Input with	H L H L 758				
OSELG3	Pull High	L L H L 720				
OSELG4		H H L L 704				
		L H L L 640				
		H L L 600				
		L L L L 480				
0141 010401	• • •	Gate driver output pins for driving the display's gate signals. The				
G[1] ~ G[840]	Output	amplitude of these outputs is from VGH to VGL. The output timing of these signals is synchronous with the rising edge of the shift clock.				
Power Supply		these signals is synchronous with the fishing edge of the shift clock.				
VPOS	Power	Supply of positive power for source outputs				
VNEG	Power	Supply of negative power for source outputs				
VCC	Power	Power for digital circuit				
GND	Power	Ground pin				
VGH		'				
	Power	Supply of positive power for the gate outputs.				
VGL	Power	Supply of negative power for the gate outputs.				
Others						
GLOSTL		For bumping test.				
TEST1~TEST2		Please do not connect to any signal or power, just let them open.				

Note: SHR, UD and MODE can not be changed during frame.

### 5. FUNCTION DESCRIPTION

### 5.1. Description

The EK79631 is an EPD IC max for 1280\*840 active matrix display, include Source driver and Gate driver. It also provides cascade function for dot expansion.

The Source driver is a selectable 1280, 1200, 1024, 960 or 800 bit long 2-bit wide serial-input parallel-output driver with level conversion on each parallel output which converts the 2 digital bits into positive, GND, or negative analog output voltages. An 16-bit input bus simultaneously inputs 8 groups of 2 bits each.

Terminal SHR, when SHR = logic 1, the data inputs are read sequentially from S[1280] to S[1] end of the device. The direction is reversed when SHR is logic 0. It is asynchronous to the clock CLK.

The two input terminals latch enable (LE) and output enable (OE) are asynchronous to the clock CLK. Terminal OE, when is logic 0, forces "S[1]...S[1280]" outputs to GND. Terminal LE controls 960 latches that are transparent when LE is logic 1 and hold the data when LE is logic 0.

The EK79631 logic is static CMOS type. The current drain depends on the operating frequency.

Each "S[1]...S[1280]" pin is switched to one of [VPOS, GND, VNEG] voltage levels according to the D[15:0] logic levels clocked into the JD79631, modified by the OE pin. The truth tables are shown in the following tables.

Table 2. Data Input Truth Table (8-bit)

ΩE	D [2n + 1]	D [2n]	SHR = H	SHR = L
OL	D [211 + 1]	נווצן ט	Output [n + 1 + 4k]	Output [4(k+1) - n]
1	0	0	GND	GND
1	0	1	VPOS	VPOS
1	1	0	VNEG	VNEG
1	1	1	GND	GND
0	X	Χ	GND	GND

Note: n = 0 to 3, k = 0 to 319.

Table 3. Source clock input Table(8-bit)

Table of Course Clock in part 1 acre (Course)									
Output channels	Latch clocks	Dummy clocks	Total clocks						
1280	320		320 + Dummy clocks						
1200	300		300 + Dummy clocks						
1024	256	≥ 10	256 + Dummy clocks						
960	240		240 + Dummy clocks						
800	200		200 + Dummy clocks						

### Note:

After the last data, it should append 10 dummy clocks at least.

Example1: If only 800 output channels in use, the total clocks should be 200+10 at least. Example2: In cascade application, if output channels are 1920, the total clocks should be 480

+10 at least.

Table 4. Data Input Truth Table (16-bit)

ΩE	D [2n + 1] D [2n]	SHR = H	SHR = L	
OL	D [211 + 1]	נווצן ט	Output [n + 1 + 8k]	Output [8(k+1) - n]
1	0	0	GND	GND
1	0	1	VPOS	VPOS
1	1	0	VNEG	VNEG
1	1	1	GND	GND
0	X	Χ	GND	GND

Note: n = 0 to 7, k = 0 to 159.

Table 5. Source clock input Table

Output channels	Latch clocks Dummy clocks		Total clocks	
1280	160		160 + Dummy clocks	
1200	150		150 + Dummy clocks	
1024	128	≥ 10	128 + Dummy clocks	
960	120		120 + Dummy clocks	
800	100		100 + Dummy clocks	

Table 6. Latch block

LE	Data in 1280-bit long 2-bit wide latch
Н	Load data into latch from shifter register
L	Hold latch data

### 5.2. Power On/Off Sequence

This IC is a high-voltage EPD driver, so it may be damaged by a large current flow if an incorrect power sequence is used. Connecting the drive powers, [VNEG, VGL] & [VPOS, VGH], after the logical power, VCC, is the recommended sequence. When shutting off the power, shut off the drive power and then the logic system or turn off all powers simultaneously.

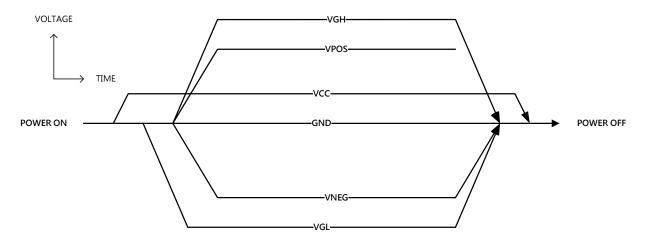


Figure 2. Power On/Off Sequence

### 5.3. Power Level

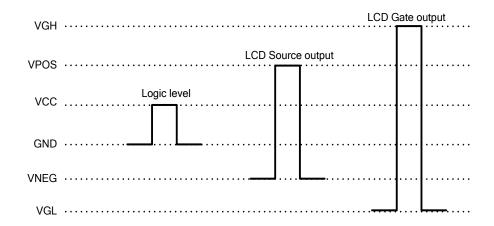


Figure 3. Signal voltage level

#### Note:

For the input signals: CLK, STL1, STL2, GLOSTL, SHR, D[15:0], OE, LE, OSELS[3:1],GCLK, STV1, STV2, UD, MODE, XON and OSELG[4:1] "High" level = VCC, "Low" level = GND.

## 5.4. Channel Selection Function

OSELS1	OSELS2	OSELS3	Source Output Channels	Valid Output Channels	Invalid Output Channels
Х	X	Н	1280CH	S1 ~ S1280	None
Н	Н	L	1200CH	S49~ S1248	S1 ~ S48,S1249~S1280 Fix to GND
L	Н	L	1024CH	S129~ S1152	S1 ~ S128,S1153~S1280 Fix to GND
Н	L	L	960CH	S161~ S1120	S1 ~ S160,S1121~S1280 Fix to GND
L	L	L	800CH	S241~ S1040	S1 ~ S240,S1041~S1280 Fix to GND

 $\mathsf{TFT}_\mathsf{TYPE} = \mathsf{L}$ 

OSELG1	OSELG2	OSELG3	OSELG4	Gate Output Channels	Valid Output Channels	Invalid Output Channels
Х	Х	Х	Н	840CH	G1 ~ G840	None
Н	Н	Н	L	825CH	G1 ~ G825	G826~ G840 Fix to VGL
L	Н	Н	L	768CH	G1 ~ G768	G769~ G840 Fix to VGL
Н	L	Н	L	758CH	G1~ G758	G759~ G840 Fix to VGL
L	L	Н	L	720CH	G101~ G820	G1~ G100, G821~ G840 Fix to VGL
Н	Н	L	L	704CH	G101~ G804	G1~ G100, G805~G840 Fix to VGL
L	Н	L	L	640CH	G101~ G740	G1~ G100, G741~ G840 Fix to VGL
Н	Ĺ	L	L	600CH	G121~ G720	G1~ G120, G721~ G840 Fix to VGL
L	L	L	L	480CH	G181 ~ G660	G1 ~ G180, G661 ~ G840 Fix to VGL

TFT\_TYPE = H

OSELG1	OSELG2	OSELG3	OSELG4	Gate Output Channels	Valid Output Channels	Invalid Output Channels	
Х	X	Х	Н	840CH	G1 ~ G840	None	
Н	Н	Н	L	825CH	G1 ~ G825	G826~ G840 Fix to VGH	
L	Н	Н	L	768CH	G1 ~ G768	G769~ G840 Fix to VGH	
Н	L	Н	L	758CH	G1~ G758	G759~ G840 Fix to VGH	
L	L	Н	L	720CH	G101~ G820	G1~ G100, G821~ G840 Fix to VGH	
Н	Н	L	L	704CH	G101~ G804	G1~ G100, G805~G840 Fix to VGH	
L	Н	L	L	640CH	G101~ G740	G1~ G100, G741~ G840 Fix to VGH	
Н	L	L	L	600CH	G121~ G720	G1~ G120, G721~ G840 Fix to VGH	
L	L	L	L	480CH	G181 ~ G660	G1 ~ G180, G661 ~ G840 Fix to VGH	

### 6. ELECTRICAL SPECIFICATION

### 6.1. Absolute Maximum Ratings

**Table 7.** Absolute Maximum Ratings (GND = 0 V)

Parameter	Symbol	Rating	Unit
Logic Supply Voltage	VCC	-0.3 to +5	V
Positive Supply Voltage	VPOS	-0.3 to +18	V
Negative Supply Voltage	VNEG	+0.3 to -18	V
Max. Drive Voltage Range	VPOS - VNEG	36	V
Supply voltage	VGH	-0.3 to +VGL+51	V
Supply voltage	VGL	-25.0 to + 0.3	V
Supply range	VGH - VGL	-0.3 to + 51	V
Operating Temp. Range	TOTR	-30 to +85	°C
Storage Temperature	TSTG	-55 to +125	°C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this data sheet is not implied. Exposure of the device to the absolute maximum ratings for an extended period may degrade the device and affect its reliability.

### 6.2. Recommended Operating Range

**Table 8.** Recommended Operating Range (GND = 0V)

Parameter	Condition	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage (1)	-	VCC	1.7	3.0	3.6	V
Supply Voltage (2)	-	VPOS	10	-	15	V
Supply Voltage (3)	-	VNEG	-15	-	-10	V
Supply Voltage (4)	-	VGH	7.0	VGL + 48	VGL + 49	V
Supply Voltage (5)	-	VGL	-20	-	VNEG - 4	V
Clock Frequency (1)	-	fGCLK	-	-	200	KHz
Clock Frequency (2)	VCC = 2.5V ~ 3.6V	fCLK	_		60	MHz
Clock Frequency (2)	VCC = 1.7V ~ 2.5V		_	-	48	IVIITZ
Operating temperature	-	$T_A$	-20	-	75	°C

### 6.3. Supply Capacitor Selection

We recommended it is necessary to connect 4.7 $\mu F$  ceramic capacitors from VCC, VGH, VGL, VPOS and VNEG to GND.

### 6.4. DC Characteristics

6.4.1. Source DC Characteristics (TA = 25°C, VCC=3.0V, GND = 0V, VPOS = 15V, VNEG = -15V, CLK=20MHz)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
High level input voltage	$V_{IH}$	-	0.8 x VCC	-	VCC	V
Low level input voltage	$V_{IL}$	-	GND	-	0.2 x VCC	V
High level output voltage	V <sub>OH</sub>	I <sub>OH</sub> = 2mA	VCC-0.5V	-	VCC	V
Low level output voltage	V <sub>OL</sub>	$I_{OL} = 2mA$	GND	-	GND+0.5V	V
Input leakage current	IL	-	-1	-	+1	μΑ
Input pull high / low	Rph / Rpl	VCC = 1.8V	200	_	1000	ΚΩ
resistance	INPH / INPL	VCC = 3.0V	100		450	
Logic static current, output inactive	I <sub>ccs</sub>	When VPOS and VNEG = 0, $V_{IN}$ = GND or VCC	-	-	30	μΑ
Logic current, output active	I <sub>CC1</sub>	Per output that is switched to VNEG.	-	-	3	mA
VPOS DC current	I <sub>POS1</sub>	Per output that is switched to VPOS.	-	-	30	μΑ
VNEG DC current	I <sub>NEG1</sub>	Per output that is switched to VNEG.	-	1	30	μΑ
VPOS Switching current	I <sub>POS2</sub>	VPOS = 15V, VNEG = -15V, Cload = 100pf, $f_{LINE}$ = 57KHz	-	-	TBD	mA
VNEG Switching current	I <sub>NEG2</sub>	VPOS = 15V, VNEG = -15V, Cload = 100pf, $f_{LINE}$ = 57KHz	-	-	TBD	mA

6.4.2. Gate DC Characteristics (TA =  $25^{\circ}$ C, VCC=3.0V, GND = 0V, VGH = 22V, VGL = -20V, GCLK=200KHz)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
High level input voltage	VIH	-	0.8 x VCC	-	VCC	V
Low level input voltage	VIL	-	0	-	0.2 x VCC	V
High level output current	IXOH	Driving current, VO = VGH - 0.5V	0.5	ı	-	mA
Low level output current	IXOL	Skin current, VO = VGL + 0.5V	-0.5	-	-	mA
Input Leakage current	IIL	-	-1	-	1	μΑ
Input pull high / low	Rph / Rpl	VCC = 1.8V	200	_	1000	ΚΩ
resistance	IXPH / IXPL	VCC = 3.0V	100	-	450	
Operating current consumption (Note 1)	ICC	VCC = 3.0V Fclk = 20KHz, No load	-	-	120	μΑ
Operating current consumption (Note 1)	IGH	VGH = 22V, Fclk = 20KHz, No load	-		300	μΑ
Operating current consumption (Note 1)	IGL	VGL = -20V Fclk = 20KHz, No load	-	-	300	μΑ

**Note 1:** For STV frequency = 60 Hz

## 6.5. AC Characteristics

6.5.1. Source AC Characteristic (TA = 25°C, VCC=3.0V, GND = 0V, VPOS = 15V, VNEG = -15V, VGL=-20V)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Clock CLK cycle time	t <sub>cy</sub>	-	16.67	50	-	nS
D15D0 setup time	t <sub>su</sub>	-	8	-	-	nS
D15D0 hold time	t <sub>h</sub>	-	8	-	-	nS
STL1/STL2 setup time	t <sub>stls</sub>	-	0.5 x t <sub>cy</sub>	-	0.8 x t <sub>cy</sub>	nS
		1280 outputs			$320 \times t_{cy} - t_{stls}$	
		1200 outputs			$300 \times t_{cy} - t_{stls}$	nS
STL1/STL2 hold time <sup>(1)</sup>	t <sub>stlh</sub>	1024 outputs	$0.5 \times t_{cy}$	-	$256 \times t_{cy} - t_{stls}$	
		960 outputs			240 x t <sub>cy</sub> - t <sub>stls</sub>	
		800 outputs			200 x t <sub>cy</sub> - t <sub>stls</sub>	
GLOSTL setup time	t <sub>glostls</sub>	-	0.5 x t <sub>cy</sub>	-	0.8 x t <sub>cy</sub>	nS
		1280 outputs			$320 \times t_{cy} - t_{stls}$	
	t <sub>glostlh</sub>	1200 outputs	0.5 x t <sub>cv</sub>	-	$300 \times t_{cy} - t_{stls}$	nS
GLOSTL hold time <sup>(1)</sup>		1024 outputs			256 x t <sub>cy</sub> - t <sub>stls</sub>	
		960 outputs			240 x t <sub>cy</sub> - t <sub>stls</sub>	
		800 outputs			200 x t <sub>cy</sub> - t <sub>stls</sub>	
LE on delay time	t <sub>LEdly</sub>	-	10.5 x t <sub>cy</sub>	-	-	nS
LE high-level pulse width	t <sub>LE</sub>	VCC=2.5V to 3.6V	300	-	-	nS
LE off delay time	t <sub>LEoff</sub>	-	200	-	-	nS
Output settling time to +/- 30mV	t <sub>OUT</sub>	Cload = 200pF	-	-	20	μS

(TA = 25°C, VCC=1.8V, GND = 0V, VPOS = 15V, VNEG = -15V, VGL= -20V)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Clock CLK cycle time	t <sub>cy</sub>	-	20.83	-	-	nS
D15D0 setup time	t <sub>su</sub>	-	10	-	-	nS
D15D0 hold time	t <sub>h</sub>	-	10	-	-	nS
STL1/STL2 setup time	t <sub>stls</sub>	-	0.5 x t <sub>cy</sub>	-	0.8 x t <sub>cy</sub>	nS
		1280 outputs			320 x t <sub>cy</sub> - t <sub>stls</sub>	
		1200 outputs			$300 \times t_{cy} - t_{stls}$	
STL1/STL2 hold time <sup>(1)</sup>	t <sub>stlh</sub>	1024 outputs	0.5 x t <sub>cy</sub>	-	256 x t <sub>cy</sub> - t <sub>stls</sub>	nS
		960 outputs			240 x t <sub>cy</sub> - t <sub>stls</sub>	
		800 outputs			200 x t <sub>cy</sub> - t <sub>stls</sub>	
GLOSTL setup time	t <sub>glostls</sub>	-	0.5 x t <sub>cy</sub>	-	0.8 x t <sub>cy</sub>	nS
		1280 outputs			$320 \times t_{cy} - t_{stls}$	
		1200 outputs			300 x t <sub>cy</sub> - t <sub>stls</sub>	
GLOSTL hold time <sup>(1)</sup>	t <sub>glostlh</sub>	1024 outputs	0.5 x t <sub>cy</sub>	-	256 x t <sub>cy</sub> - t <sub>stls</sub>	nS
		960 outputs			240 x t <sub>cy</sub> - t <sub>stls</sub>	
		800 outputs			200 x t <sub>cy</sub> - t <sub>stls</sub>	
LE on delay time	t <sub>LEdly</sub>	-	10.5 x t <sub>cy</sub>	-	-	nS
LE high-level pulse width	t <sub>LE</sub>	VCC=1.7V to 2.5V	300	-	-	nS
LE off delay time	t <sub>LEoff</sub>	-	200	-	-	nS
Output settling time to +/- 30mV	t <sub>OUT</sub>	Cload = 200pF	-	-	20	μS

Note: (1)For 8 bit.

6.5.2. Gate AC Characteristic (TA = 25°C, VCC = 3.0V, GND = 0V, VGH = 22V, VGL = -20V)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Clock rise time	Trck	10% to 90%	-	-	100	nS
Clock fall time	Tfck	90% to 10%	-	-	100	nS
Clock pulse width (low)	Tclkl	-	500	-	-	nS
Clock pulse width (high)	Tclkh	-	500	-	-	nS
Clock frequency	Fclk	-	-	-	200	KHz
XON pulse width	t <sub>WXON</sub>	-	10	-	-	μs
XON to output delay time	t <sub>PD</sub>	CL=300pF	-	-	20	μs
STV rise time	Trstv	10% to 90%	-	-	100	nS
STV fall time	Tfstv	90% to 10%	-	-	100	nS
STV setup to Clock	Tsu	-	100	-	Tclkh-100	nS
STV hold from Clock	Th	-	100	-	Tclkh-100	nS
Output transfer delay time	Td	CL = 300pf,	-	TBD	-	uS
Output rise time	Tr	CL = 300pf, 10% to 90%	-	-	1	uS
Output fall time	Tf	CL = 300pf, 90% to10%	-	-	1	uS
VCC rise time	Ton	-	-	-	20	ms
VCC fall time	Toff	-	-	-	20	ms
VCC waiting time	Toff-on	-	700	-	-	ms

 $(TA = 25^{\circ}C, VCC = 1.8V, GND = 0V, VGH = 22V, VGL = -20V)$ 

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Clock rise time	Trck	10% to 90%	-	-	100	nS
Clock fall time	Tfck	90% to 10%	-	-	100	nS
Clock pulse width (low)	Tclkl	-	1000	ı	-	nS
Clock pulse width (high)	Tclkh	-	1000	-	-	nS
Clock frequency	Fclk	-	-	-	200	KHz
XON pulse width	t <sub>WXON</sub>	-	10	ı	-	μs
XON to output delay time	t <sub>PD</sub>	CL=300pF	-	ı	20	μs
STV rise time	Trstv	10% to 90%	-	-	100	nS
STV fall time	Tfstv	90% to 10%	-	-	100	nS
STV setup to Clock	Tsu	-	100	ı	Tclkh-100	nS
STV hold from Clock	Th	-	100	ı	Tclkh-100	nS
Output transfer delay time	Td	CL = 300pf,	-	TBD	-	uS
Output rise time	Tr	CL = 300pf, 10% to 90%	-	-	1	uS
Output fall time	Tf	CL = 300pf, 90% to10%	-	-	1	uS
VCC rise time	Ton	-	-	ı	20	ms
VCC fall time	Toff	-	-	-	20	ms
VCC waiting time	Toff-on	-	700	-	-	ms

## 6.6. Operating Timing

## 6.6.1. Source

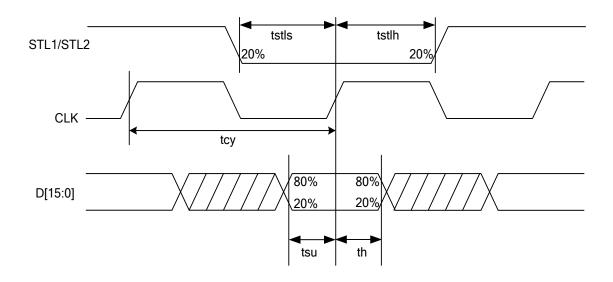


Figure 4. Clock and Data Timing

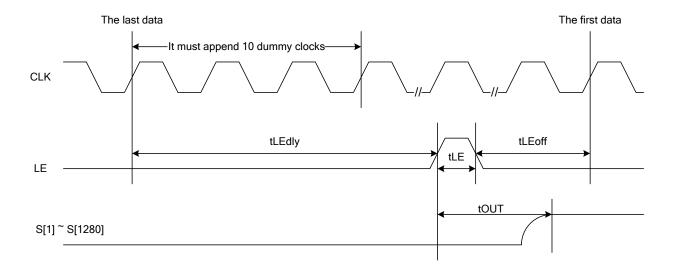


Figure 5. Output Latch / Control Signals

Note: After the last data, CLK must append 10 dummy clocks at least.

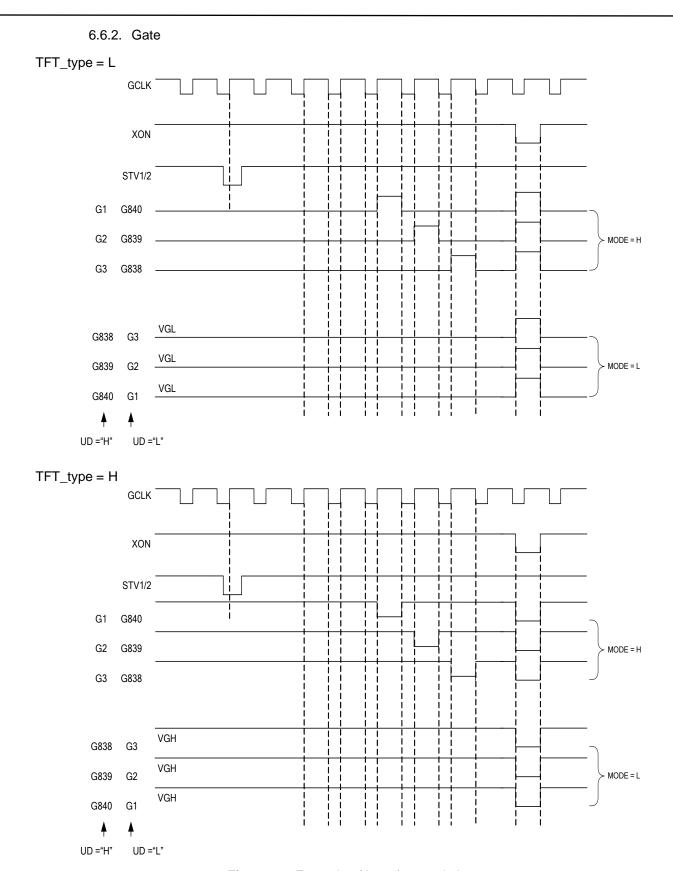


Figure 6. Example of input/output timing

## 6.7. Timing Waveform

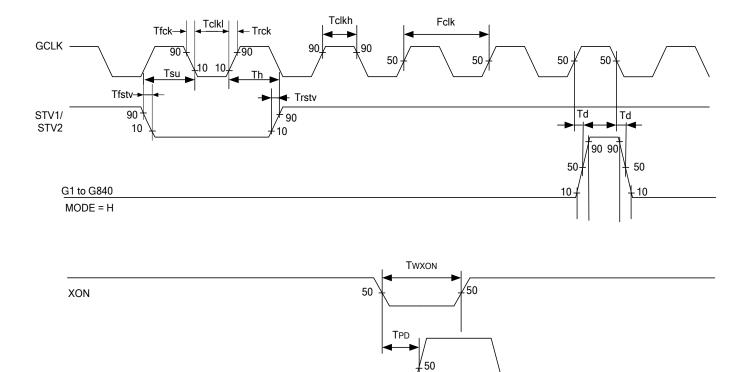


Figure 7. Timing Waveform

## 6.8. VCC on/off time

G1 to G840

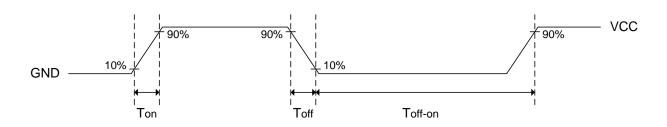


Figure 8. VCC on/off time

### 7. DEFINITIONS

### 7.1. Data Sheet Status

Tentative Data Sheet	This data sheet contains Tentative data; supplementary data may be published later.
Data Sheet	This data sheet contains final product specifications.

Contents in the document are subject to change without notice.

### 7.2. Life Support Application

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Fitipower customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify fitipower for any damages resulting from such improper use or sale.